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particles having a median particle diameter of greater than 10 microns and a maximum diameter of about 50 microns, said particles are selected from the group consisting of glass microspheres, ceramic microspheres, spheroidal minerals, polymer microspheres and metal microspheres and the resin of the powder coating composition is selected from the group consisting of saturated polyesters, unsaturated polyesters, acrylic resins, acrylate resins, polyester-urethanes, acrylic-urethanes, epoxy, epoxy-polyester, polyester-acrylics, epoxy-acrylics, polyamides, polyvinylchloride, polyethylene, polyethylene terephthalate, polybutylene terephthalate and polypropylene.

Cancel Claims 8 and 9

REMARKS

The claims have been amended to more clearly point out the invention and obviate the rejections under 35 U.S.C. § 112.

In the Office Action, claims 1 - 9 were rejected under 35 U.S.C. § 112 for failing to point out the invention on the basis that it is not clear what is meant by the term "low gloss". "Low gloss" is a term that is well known and understood in the art and needs no further explanation. For example, Dumain US Patent 6,093,774, which was cited by the Examiner and is directed to low gloss powder coatings, on col. 1, lines 39-42 describes low gloss coatings as having a matte finish and are useful for automotive interiors, wheel rims, bumpers and the like.

In the Office Action the Examiner stated that there was no recitation of thermosetting and thermoplastic resins in claim 5. Claim 5 has been amended to the use of the preferred resin listed in claim 9 which now has been canceled, thereby obviating the 112 rejection.

**Rejection under 35 U.S.C. § 102**

Claims 1-2 and 4 were rejected under 35 U.S.C. § 102 (e) as being anticipated by Maeda et al. U.S. 6,190,787 taken in view of the evidence given in Dumain U.S. 6,093,774. However, Maeda is not directed to a low gloss powder coating composition, but to an epoxy resin composition used to seal semiconductors. Maeda, in addition to the epoxy resin, contains a phenol resin curing agent, a curing accelerator, an inorganic filler and zinc molybdate. Such a composition would not form a matte film suitable for use in automobiles. In particular, Maeda uses fused